Software Technology Parks of India - Bangalore

Annexure - XIII

Application for Bonding Request

Date

To

The Director,
Software Technology Parks of India,
Bangalore

Dear Sir,

Subject: Request for Bonding

1. Name of the Company	
2. Location of the Unit	
3. Contact Person	
4. Telephone Nos.	
5. Extension No.	
6. Mobile No.	
7. Pager No.	
8. PBWHL No, Date and Validity date	
9. Import Approval No. & date	
10. Bill of Entry No.	
11. Bill of Entry Date	

Note : Bonding e-mail id exim.bonding@blr.stpi.in;